

CONTACTLESS CIRCUIT TESTING FOR ADAPTIVE WAFER PROCESSING**ABSTRACT OF THE DISCLOSURE**

A system and method for measuring circuits on an integrated circuit substrate includes a measurement circuit formed on the integrated circuit substrate that measures at least one characteristic of an integrated circuit. The measurement circuit has a power transfer device including a power transfer component, which receives energy from a source where the source does not make physical contact with the integrated circuit substrate to transfer power to the measurement circuit. Measurements are taken to provide feedback for in-situ adjustments to circuit parameters and responses.